



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-02-21
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Floriana San Biagio	<b>Representative Title</b>	AMG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**


<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	KD6R*R014AAY	A	BO2A	2017-02-21
Amount	UoM	Unit type	ST ECOPACK Grade	
54.82	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	5x4.4x0.9	14	gull wing	
Comment	Package: 6R TSSOP 14 BODY 4.4 PITCH 0.65; MDF valid for M74HC14YTTR			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	KD6R*R014AAV					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.721	mg	supplier	die	Silicon (Si)	7440-21-3		1.678	mg	975015	30609
				supplier	metallization	Aluminium (Al)	7429-90-5		0.014	mg	8135	255
				supplier	Passivation	Silicon Nitride	12033-89-5		0.002	mg	1162	36
				supplier	Passivation	Silicon Oxide	7631-86-9		0.027	mg	15689	493
Leadframe	Copper & its alloys	25.813	mg	supplier	alloy	Copper (Cu)	7440-50-8		24.545	mg	950877	447738
				supplier	alloy	Nickel (Ni)	7440-02-0		0.765	mg	29636	13955
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.038	mg	1472	693
				supplier	alloy	Silicon (Si)	7440-21-3		0.166	mg	6431	3028
				supplier	metallization	Nickel (Ni)	7440-02-0		0.178	mg	6896	3247
				supplier	metallization	Palladium (Pd)	7440-05-3		0.006	mg	232	109
				supplier	metallization	Gold (Au)	7440-57-5		0.005	mg	194	91
				supplier	metallization	Silver (Ag)	7440-22-4		0.110	mg	4261	2007
Die attach	Other Organic Materials	0.343	mg	supplier	glue	Silver (Ag)	7440-22-4		0.302	mg	880466	5509
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.017	mg	49563	310
				supplier	glue	Urethane Methacrylate Resin	5888-33-5		0.017	mg	49563	310
				supplier	glue	Acrylate polymer	87320-05-6		0.007	mg	20408	128
Bonding wires	Other inorganic materials	0.127	mg	supplier	wire	Copper (Cu)	7440-50-8		0.127	mg	1000000	2317
Encapsulation	Other Organic Materials	26.816	mg	supplier	mold compound	Silica, vitreous	60676-86-0		23.517	mg	876976	428986
				supplier	mold compound	Epoxy resin	85954-11-6		1.073	mg	40013	19573
				supplier	mold compound	Epoxy	29690-82-2		1.073	mg	40013	19573
				supplier	mold compound	phenol resin	Proprietary		0.805	mg	30019	14684
				supplier	mold compound	additive	Proprietary		0.268	mg	9994	4889
				supplier	mold compound	carbon black	1333-86-4		0.080	mg	2983	1459